



Save Time

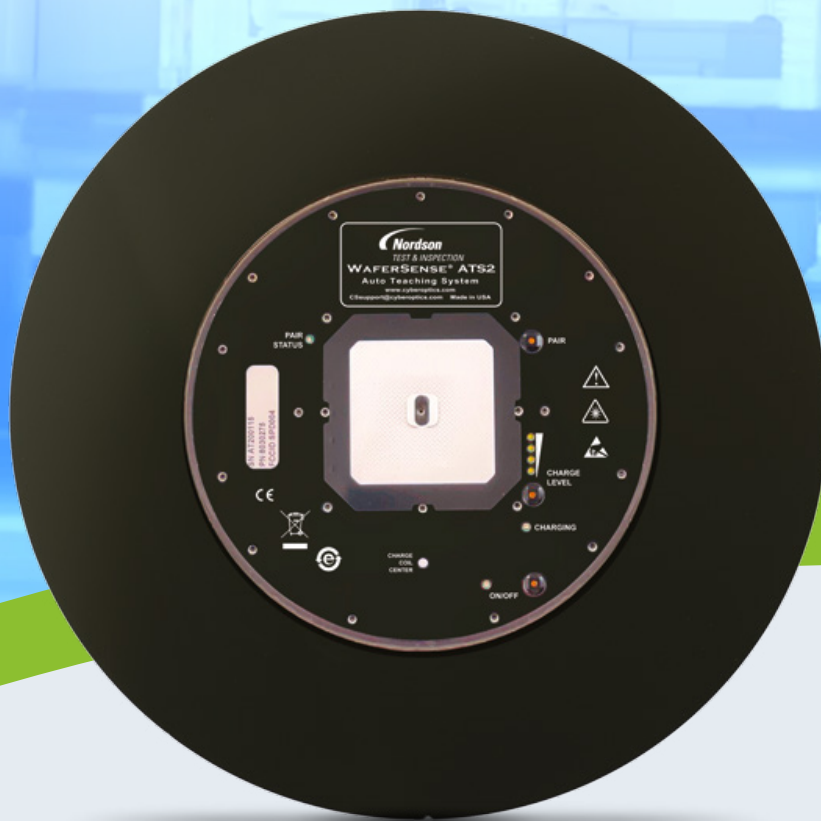


Save Expense



Improve Yields

Semiconductor fabs and OEMs worldwide value the accuracy, precision and versatility of the WaferSense ATS2 – The most efficient and effective wireless measurement device for wafer handoff teaching.



WS

WaferSense®

Auto Teaching System™ (ATS2)

Metrology Sensors

Speed achieving accurate wafer hand-off calibration, proper alignment and set-ups.

“Sees” inside semiconductor equipment to capture three dimensional offset data (x, y and z) to quickly teach wafer transfer positions with accuracy to 100µm.

Improve Yields

Improve yields and lower particulate contamination with accurate wafer handoff calibration.

- Capture offset data for accurate calibration of transfer positions as the wafer-like ATS2 moves through your semi-conductor equipment.
- Improve the yield of your manufacturing process with calibrated equipment.

Repeatable & Reproducible

Achieve repeatable and reproducible semiconductor equipment setups.

- Eliminate technician-to-technician variation with the ATS2 calibration process enabling repeatable and reproducible setup and maintenance checks.

Reduce Equipment Downtime

Equipment Downtime from hours to minutes.

- Save time troubleshooting with the wireless and vacuum compatible ATS2, as equipment stays sealed during inspection.
- Increase equipment availability and reduce manpower and consumable expense.

Speed Trouble-shooting

Speed trouble-shooting and lower consumable expense with visual inspection.

- Receive real-time images as robots move the ATS2 through the tool. New CyberSpectrum™ software graphical user interface provides
- x, y and z offsets that eliminate guesswork. Search for lost wafers, verify that pedestals are free of debris without opening the tool.

For more information, speak with your Nordson representative or contact your Nordson regional office

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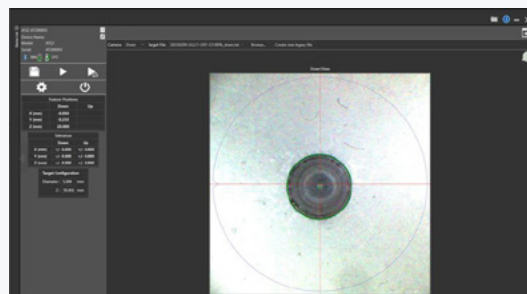
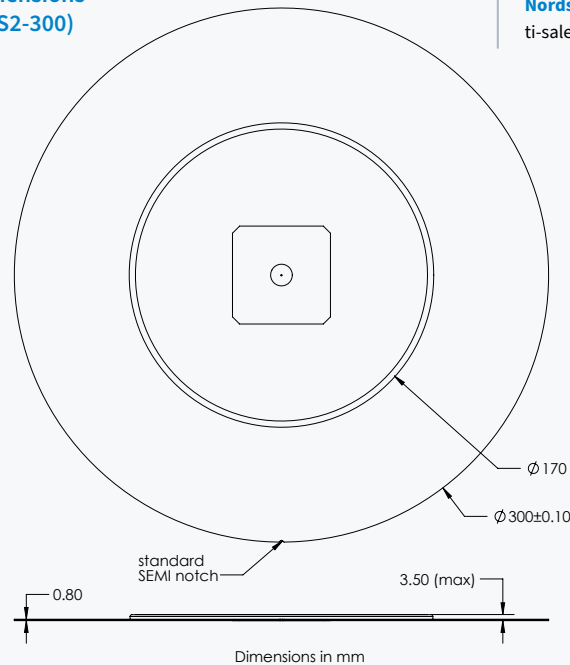
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Specifications	
Wireless, wafer-shaped and battery-powered	Available in 200mm and 300mm
Part Numbers	200 mm (8030276), 300 mm (8030275), 300 mm with Quartz Ring (8030423)
Two on-board cameras	Reports x-y-z offset from the teaching wafer to a target inside the equipment so you can teach wafer transfer coordinates. Cameras: 1 upward, 1 downward. Color images with white light illumination.
Software	CyberSpectrum
Durable housing	Chemically hardened glass (CHG)
Lightweight, wafer-like mass and mass distribution	165 grams ± 25 grams (200 mm), 225 grams ± 25 grams (300 mm)
Sensor edge and body thickness	Edge: 0.80 mm; Body: 3.5 mm (300mm)
Operating pressure	<10 ⁻⁶ to 760 torr
Operating temperature	20 to 60 °C
Communication	Bluetooth, WiFi
Operating system	Windows 10
Product components	Teaching device, charging clean case, carrying suitcase, accessory communication gateway
Calibration	Factory recalibration recommended annually
Battery-duration	>2 hrs. per charge
Working distance	6.5 mm to 45 mm
Nominal working distance	10 mm (downward), 12mm (upward)
Measurement Repeatability	0.025 mm for X and Y position at nominal focus distance ¹
Accuracy	0.05 mm for X and Y position at nominal focus distance ²

Dimensions (ATS2-300)



Real-time data.

CyberSpectrum™ Software

CyberSpectrum: Displays real-time video and measurements of target features, logs offsets and user comments. Allows teaching of circular, square and crossed features. Review functionality integrated; replays log file data for review and analysis.

1) Measured on test artifact under identical conditions. 2) Measured on test artifact in atmospheric pressure room temp